

R2A20134EVB-TINW

R19AN0027EJ0100

Rev.1.00

R2A20134 Evaluation Board for LED Tube Lamp

Sep 27, 2013

1. Overview

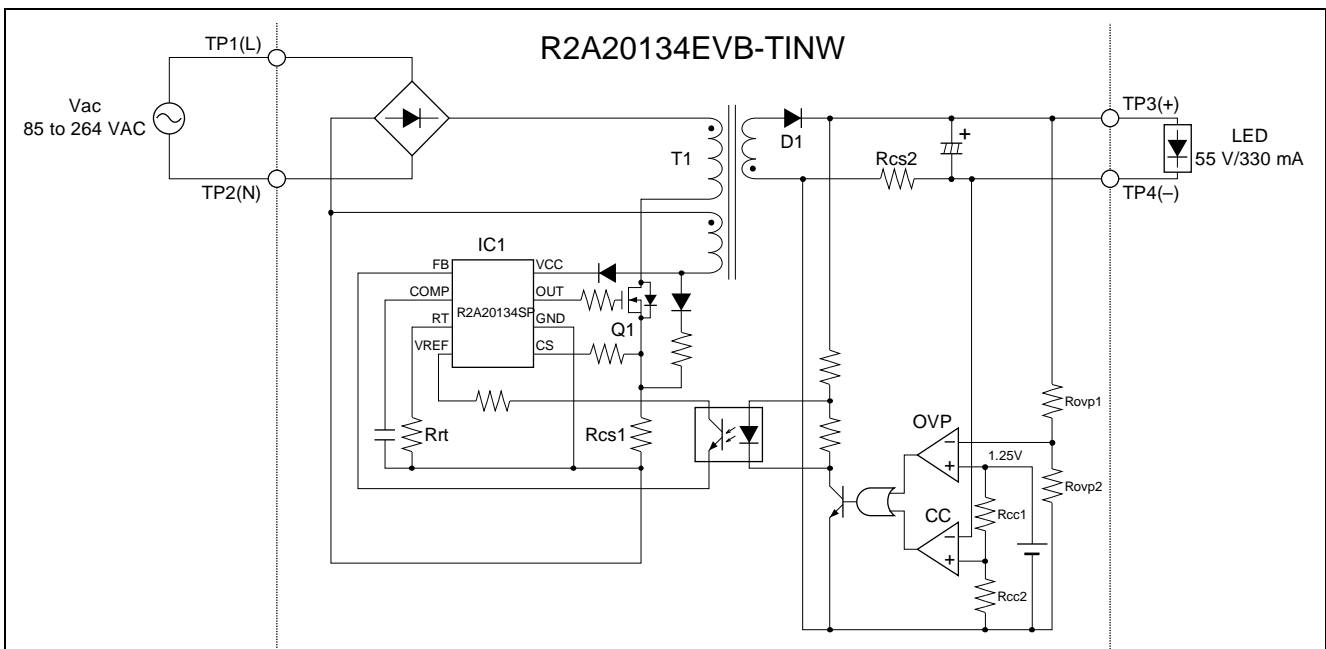
The R2A20134EVB-TINW is an LED driver IC evaluation board for LED tube lamp. All the components to control LED lighting system are onboard, it is easy to start evaluation by supplying power and connecting LED load. The board has a step-down flyback circuit, operates in constant current mode, and features high efficiency, high power factor, low THD, low ripple voltage, and low noise. It complies with harmonic current limitation (IEC 61000-3-2 Class C).

For evaluating this board, please refer to the R2A20134SP data sheet as well.

2. Specification

No.	Item	Specification
1	Input voltage range	85 to 264 VAC (single phase 47 to 63 Hz)
2	Output power	18 W (max.)
3	Output voltage	55 V (typ.)
4	Output current	330 mA (typ.)
5	Efficiency	85% or more (when $V_{in} = 100$ to 240 VAC)
6	Power factor	0.95 or more (when $V_{in} = 100$ to 240 VAC)
7	Switching frequency	Variable (minimum switching frequency: 50 kHz)
8	Operation mode	Critical Conduction Mode
9	Board	Two layers / glass epoxy (FR4) / dual-sided mount
10	Size (W ´ D ´ H)	425 mm ´ 20 mm ´ 10 mm (component side)

3. Board System Diagram and Connection

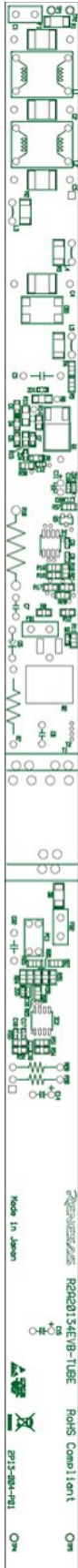




Connection Method

- (1) Connect LED load ($V_F = 55$ V/330 mA) between TP3 (+) and TP4 (-). Take care of the polarity.
- (2) Connect an AC power supply to TP1 and TP2.

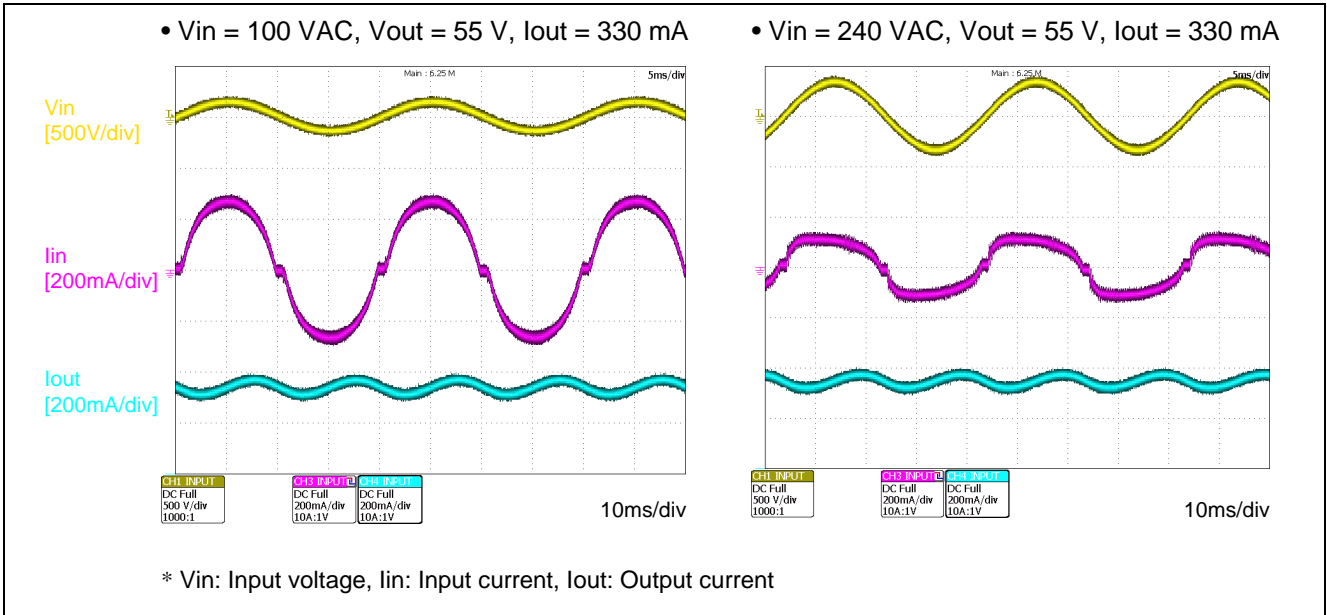
⚠ While the board is energized, in parts of the board could be at high voltage. Take care to handle the board.
Turn the AC power supply on with LED load connected between TP3 (+) and TP4 (-).

4. PCB Layout

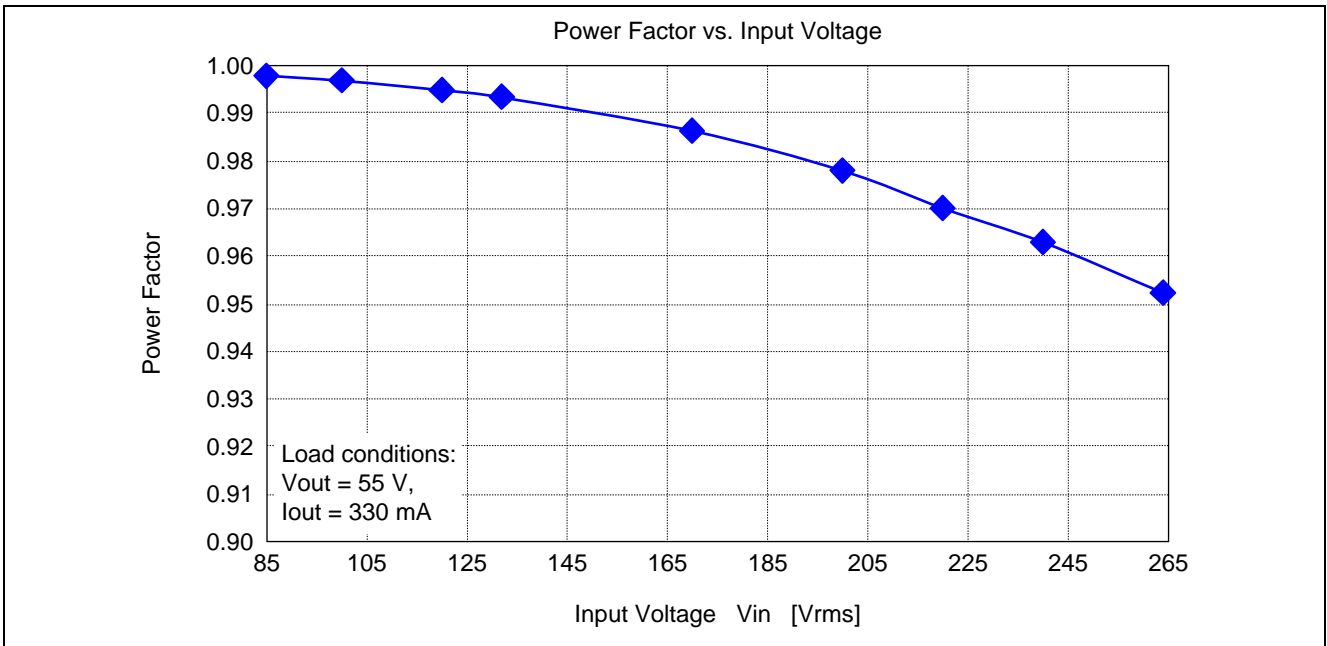
<ul style="list-style-type: none">• Components mounting	 Detailed PCB layout showing the placement of various electronic components such as resistors, capacitors, and integrated circuits. The components are arranged in a linear fashion along the length of the board. At the bottom of the layout, there is a legend and text: "R2A20134EVB-TUBE ROHS Compliant", "Made In Japan", "2013-08-15", and "Cm".	<ul style="list-style-type: none">• Layout pattern (Top)	 The top layer layout pattern of the PCB, showing the copper traces and pads in blue. The layout is symmetrical and follows the component placement shown in the first diagram.	<ul style="list-style-type: none">• Layout pattern (Bottom)	 The bottom layer layout pattern of the PCB, showing the copper traces and pads in red. The layout is symmetrical and complements the top layer.
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5. Performance Data

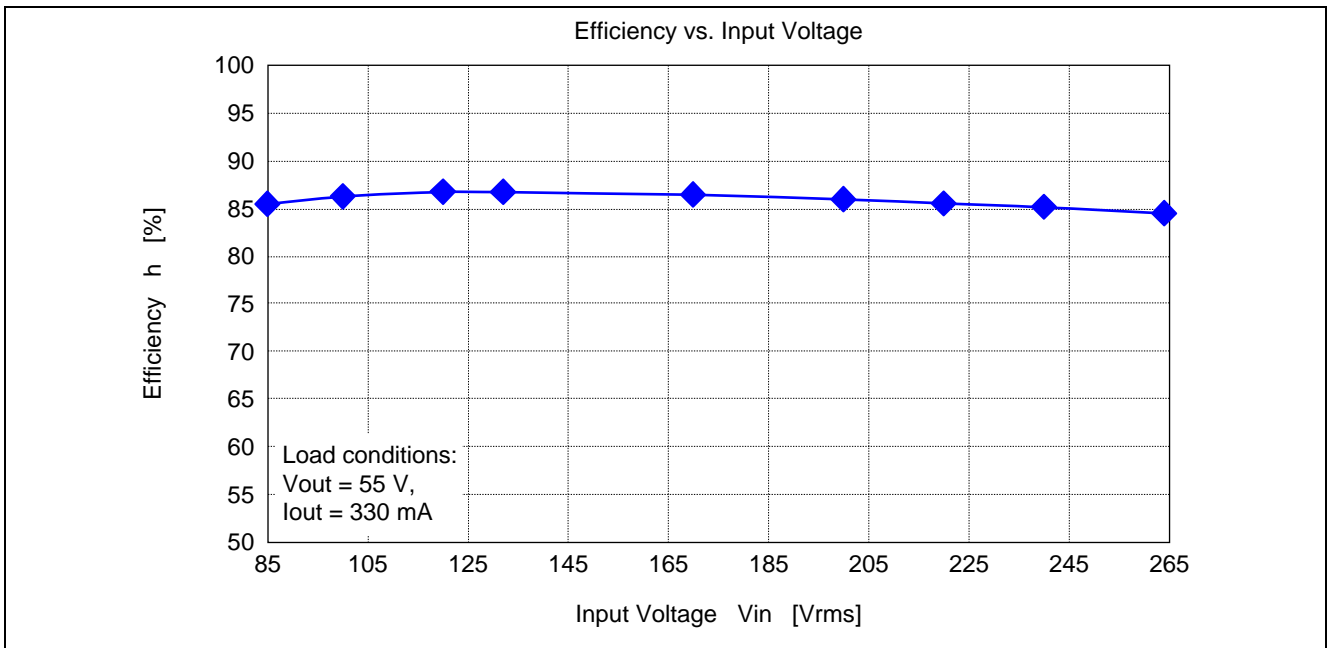
5.1 Operation Waveform



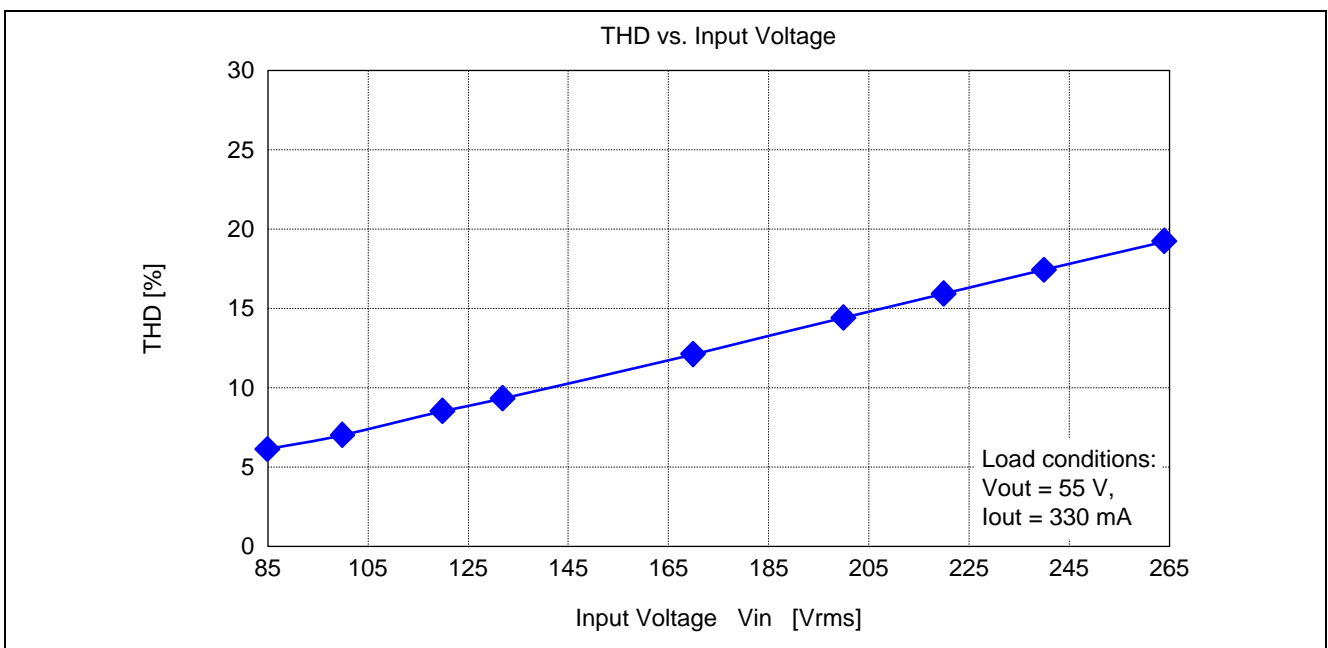
5.2 Power Factor



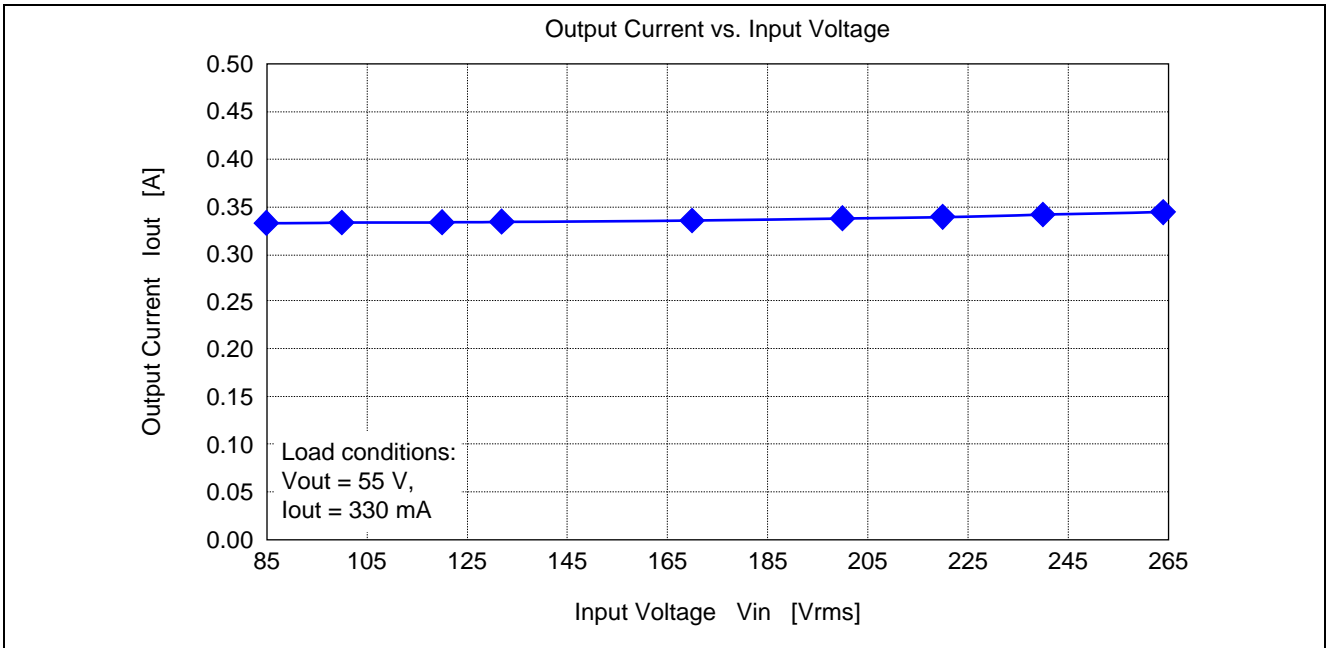
5.3 Efficiency



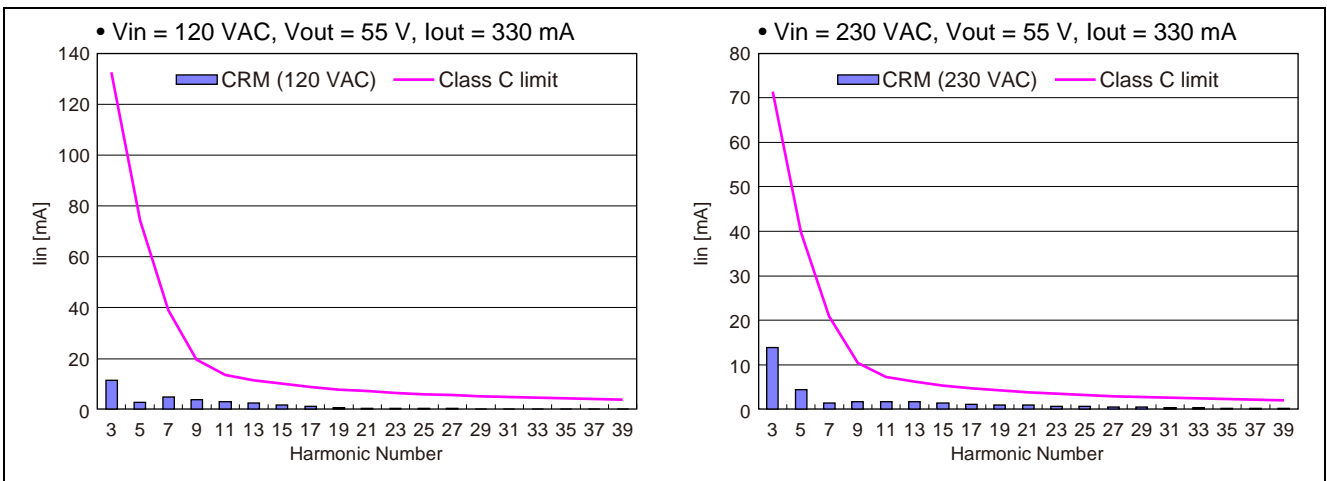
5.4 THD (Total Harmonic Distortion)



5.5 Output Current

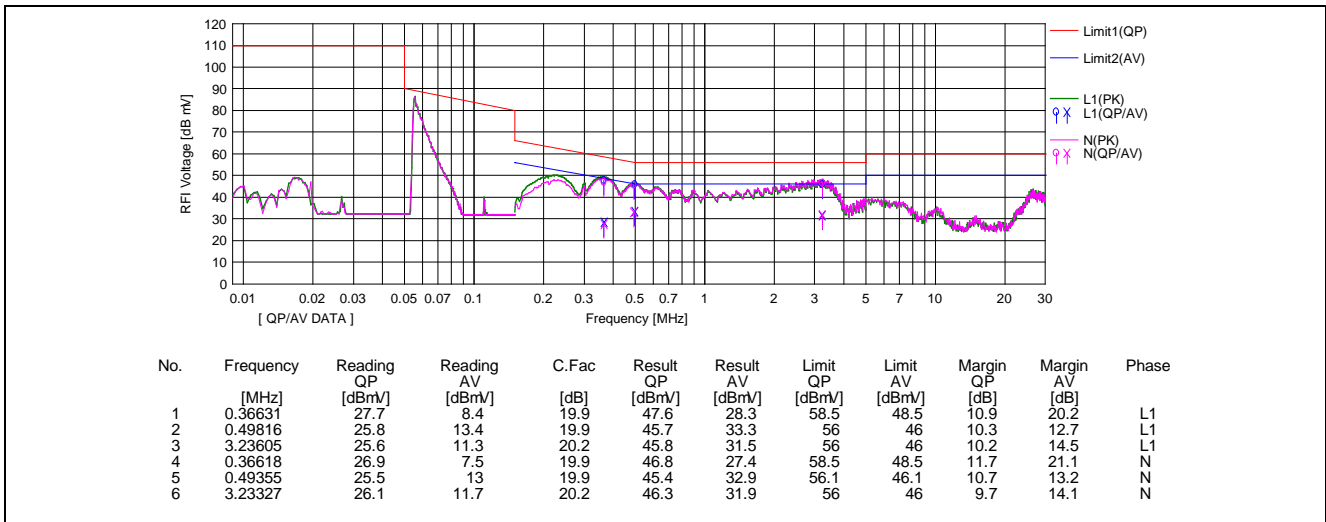


5.6 Harmonic Current

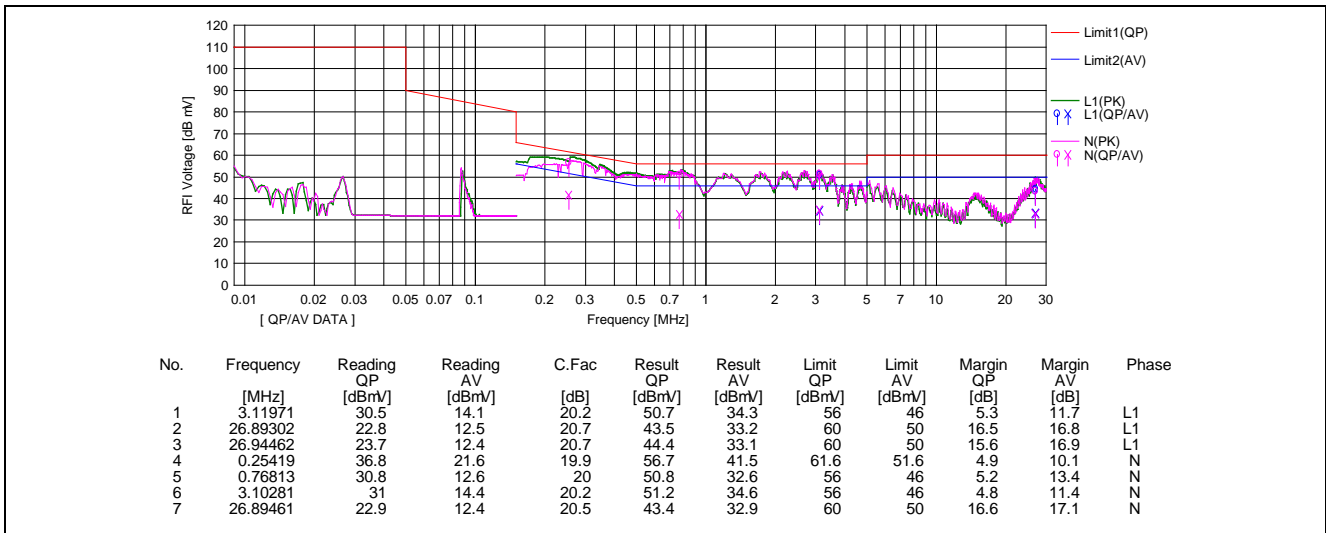


5.7 Conducted EMI (CISPR15)

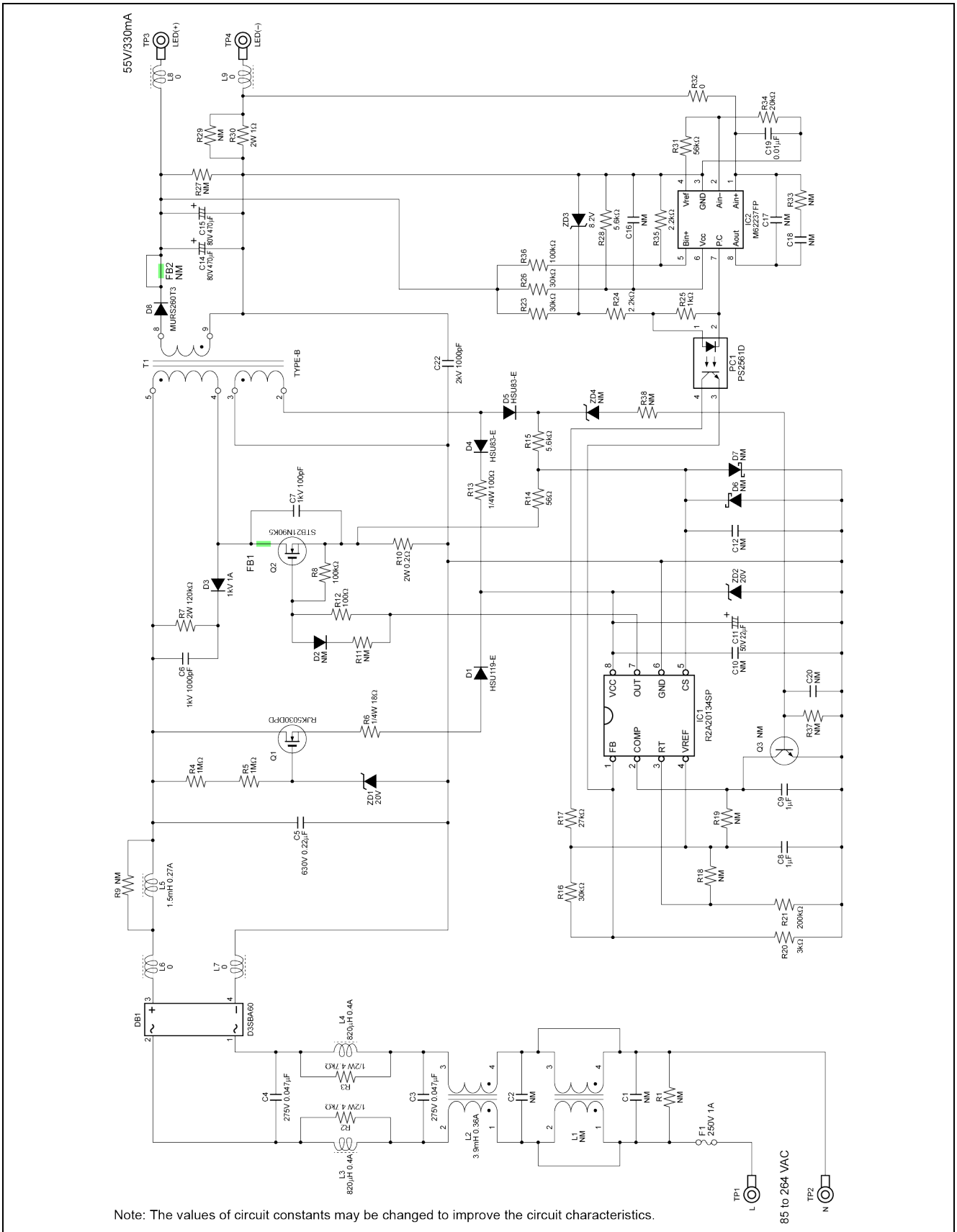
• Vin = AC100 V, 50 Hz, LED load (VF = 55 V), Iout = 330 mA



• Vin = AC240 V, 50 Hz, LED load (VF = 55 V), Iout = 330 mA



6. Schematic



7. Bill of Materials

Symbol	Parts Name	Catalog No.	Q	Rating		Manufacturer
IC1	Control IC	R2A20134SP	1			Renesas Electronics
IC2	Constant voltage/current control IC	M62237FP	1			Renesas Electronics
C1	X Capacitor	Not Mount	1			
C2	X Capacitor	Not Mount	1			
C3	X Capacitor	LE473	1	275V	0.047nF	Okaya Electric
C4	X Capacitor	LE473	1	275V	0.047nF	Okaya Electric
C5	Ceramic Capacitor	RDED72J224K5B1	1	630V	0.22nF	Murata Manufacturing
C6	Ceramic Capacitor	DESD33A102KN2A	1	1000V	1000pF	Murata Manufacturing
C7	Ceramic Capacitor	DESD33A101KN2A	1	1000V	100pF	Murata Manufacturing
C8	Chip Capacitor	GRM188R71E105KA12D	1	25V	1nF	Murata Manufacturing
C9	Chip Capacitor	GRM188R71E105KA12D	1	25V	1nF	Murata Manufacturing
C10	Chip Capacitor	Not Mount	1			
C11	Electrolytic Capacitor	PX	1	50V	22nF	Rubycon
C12	Chip Capacitor	Not Mount	1			
C13	Unused number					
C14	Electrolytic Capacitor	TXW	1	80V	470nF	Rubycon
C15	Electrolytic Capacitor	TXW	1	80V	470nF	Rubycon
C16	Chip Capacitor	Not Mount	1			
C17	Chip Capacitor	Not Mount	1			
C18	Chip Capacitor	Not Mount	1			
C19	Chip Capacitor	GRM188R11H103KA01D	1	25V	0.01nF	Murata Manufacturing
C20	Chip Capacitor	Not Mount	1			
C21	Unused number					
C22	Ceramic Capacitor	DEBF33D102ZD1B	1	2000V	1000pF	Murata Manufacturing
Q1	MOSFET	RJK5030DPD	1	500V	5A	Renesas Electronics
Q2	MOSFET	STB21N90K5	1	900V	18.5A	ST Micro
Q3	Transistor	Not Mount	1			
L1	Common mode choke coil	Not Mount	1			
L2	Common mode choke coil	LF1290NP-392	1	0.36A	3.9mH	Sumida
L3	Radial lead inductor	10RHT2	1	0.4A	820mH	TOKO
L4	Radial lead inductor	10RHT2	1	0.4A	820mH	TOKO
L5	Radial lead inductor	10RHT2	1	0.27A	1.5mH	TOKO
L6	Chip resistor	CRCW12060000Z0EA	1		0W	VISHAY
L7	Chip resistor	CRCW12060000Z0EA	1		0W	VISHAY
L8	Chip resistor	CRCW12060000Z0EA	1		0W	VISHAY
L9	Chip resistor	CRCW12060000Z0EA	1		0W	VISHAY
T1	Transformer	TYPE-B	1	600mH		SMI
PC1	Photo coupler	PS2561D-1	1			Renesas Electronics
DB1	Bridge diode	S1NB60	1	600V	1A	Shindengen Electric
D1	Rectifying diode	HSU119-E	1	80V	100mA	Renesas Electronics
D2	Schottky barrier diode	Not Mount	1			
D3	Fast recovery diode	D1NK100	1	1kV	1A	Shindengen Electric
D4	High voltage diode	HSU83-E	1	250V	100mA	Renesas Electronics
D5	High voltage diode	HSU83-E	1	250V	100mA	Renesas Electronics
D6	Zener diode	Not Mount	1			
D7	Zener diode	Not Mount	1			
D8	Fast recovery diode	MURS260T3	1	600V	2A	ON Semiconductor
ZD1	Zener diode	RKZ20B2KJ	1	150mW	20V	Renesas Electronics
ZD2	Zener diode	RKZ20B2KJ	1	150mW	20V	Renesas Electronics
ZD3	Zener diode	RKZ8.2B2KJ	1	150mW	8.2V	Renesas Electronics
ZD4	Zener diode	Not Mount	1			
R1	Chip resistor	Not Mount	1			
R2	Chip resistor	MCR50JZH472	1	1/2W	4.7kΩ	ROHM
R3	Chip resistor	MCR50JZH472	1	1/2W	4.7kΩ	ROHM
R4	Chip resistor	RK73B2ATD105J	1	1/8W	1MΩ	KOA
R5	Chip resistor	RK73B2ATD105J	1	1/8W	1MΩ	KOA
R6	Chip resistor	RK73B2ATD180J	1	1/4W	18Ω	KOA
R7	Metal oxide film resistor	MO2C	1	2W	120kΩ	KOA
R8	Chip resistor	RK73B2ATD104J	1	1/8W	100kΩ	KOA
R9	Chip resistor	Not Mount	1			
R10	Wire-wound resistor	NKN200JT-73-0R2	1	2W	0.2Ω	Yageo
R11	Chip resistor	Not Mount	1			
R12	Chip resistor	RK73B2ATD101J	1	1/8W	100Ω	KOA
R13	Chip resistor	RK73H2BTTD1000F	1	1/4W	100Ω	KOA
R14	Chip resistor	RK73B2ATD560J	1	1/8W	56Ω	KOA
R15	Chip resistor	Not Mount	1			
R16	Chip resistor	RK73B2ATD303J	1	1/8W	30kΩ	KOA
R17	Chip resistor	RK73B2ATD273J	1	1/8W	27kΩ	KOA
R18	Chip resistor	Not Mount	1			
R19	Chip resistor	Not Mount	1			
R20	Chip resistor	RK73B2ATD302J	1	1/8W	3kΩ	KOA
R21	Chip resistor	RK73B2ATD204J	1	1/8W	200kΩ	KOA
R22	Unused number					
R23	Chip resistor	RK73B2ATD303J	1	1/8W	30kΩ	KOA
R24	Chip resistor	RK73B2ATD222J	1	1/8W	2.2kΩ	KOA
R25	Chip resistor	RK73B2ATD102J	1	1/8W	1kΩ	KOA
R26	Chip resistor	RK73B2ATD303J	1	1/8W	30kΩ	KOA
R27	Chip resistor	Not Mount	1			
R28	Chip resistor	RK73B2ATD562J	1	1/8W	5.6kΩ	KOA
R29	Metal film resistor	MOSX1C	1	1W	1Ω	KOA
R30	Metal film resistor	Not Mount	1			
R31	Chip resistor	RK73B2ATD563J	1	1/8W	56kΩ	KOA
R32	Chip resistor	RK73Z2ATD	1	1A	0Ω	KOA
R33	Chip resistor	Not Mount	1			
R34	Chip resistor	Not Mount	1			
R35	Chip resistor	RK73B2ATD222J	1	1/8W	2.2kΩ	KOA
R36	Chip resistor	RK73B2ATD104J	1	1/8W	100kΩ	KOA
R37	Chip resistor	Not Mount	1			
R38	Chip resistor	Not Mount	1			
F1	Fuse	39211000440	1	250V	1A	Littelfuse
FB1	Ferrite bead	BL02RN2R1M2B	1			Murata Manufacturing
FB2	Ferrite bead	Jumper	1			

Note: The components may be changed to improve the circuit characteristics.

8. Design Guide

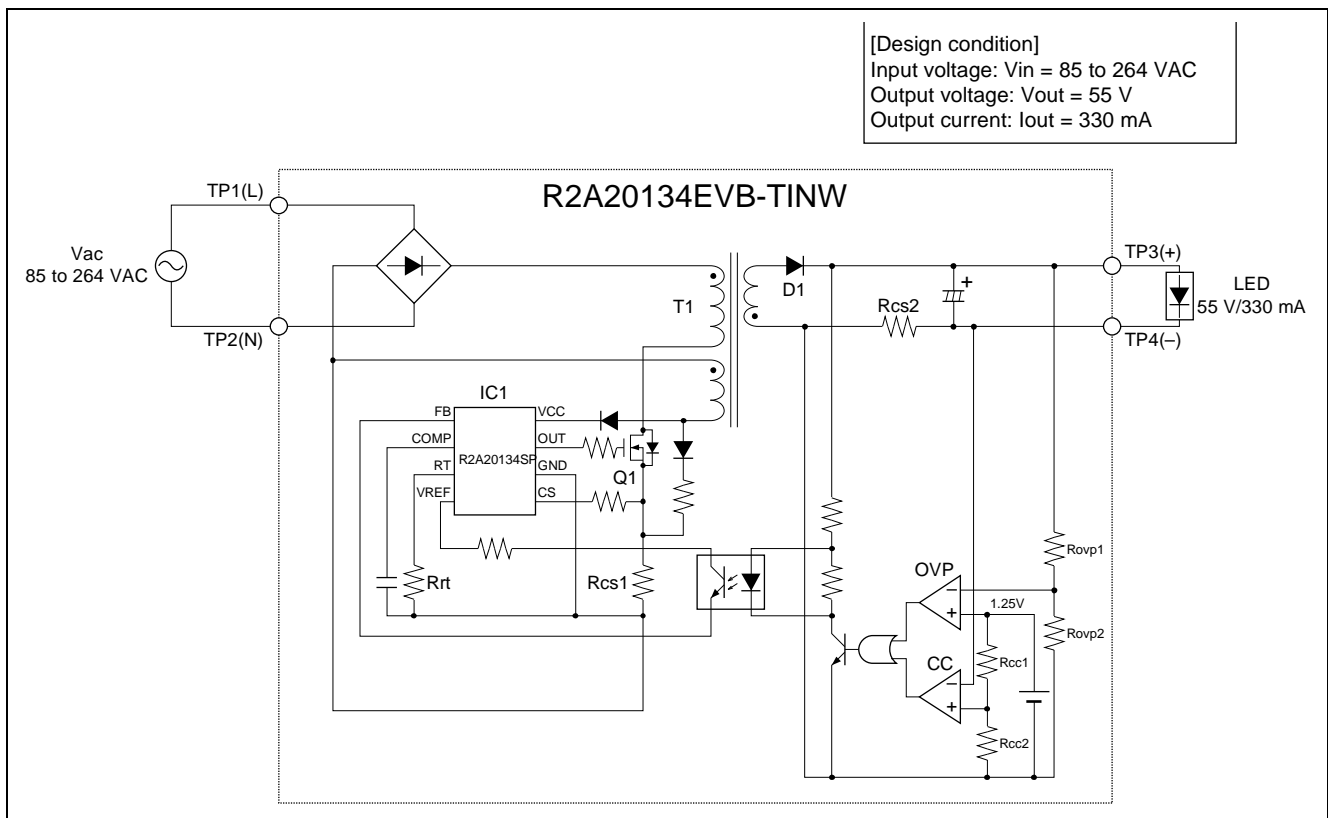


Figure 8.1 R2A20134EVB-TINW Circuit

This evaluation board operates in constant current (CC) mode. The board controls the output current I_{out} to be constant. I_{out} and the COMP pin voltage are constant, so current I_1 , which flows into the primary side of transformer T1, is proportional to input voltage V_{in} . The input current I_{in} is generated by smoothing I_1 , so I_{in} is also proportional to V_{in} . This leads to the good power factor and THD (total harmonic distortion) characteristics (refer to Figure 8.3).

8.1 Setting Switching Frequency

The frequency is generally in the range from 20 to 100 kHz, both in consideration of efficiency and so that it is not in the range of audible frequencies.

The minimum oscillation frequency is set to 50 kHz on this evaluation board.

8.2 Selection of Switching Frequency Setting Resistance R_{rt}

When the evaluation board operates in current critical mode, the RT pin is pulled down to GND by the R_{rt} resistor with a value of several hundred kW. The value of R_{rt} on the board is 200 kW.

8.3 Selection of Transformer (T1)

8.3.1 Design Example of Transformer

- The peak value of the current in the primary-side transformer, I_1 , and the peak value of the current in the secondary-side transformer, I_2 , are calculated.

$$I_1(\text{peak}) = \frac{2}{D_{on}} \times I_{in}(\text{peak}) = \frac{2 \sqrt{2} P_{out}}{D_{on} V_{in}(\text{min}) h} [\text{A}] = \frac{2 \times \sqrt{2} \times 18}{0.45 \times 80 \times 0.85} = 1.66[\text{A}]$$

$$I_2(\text{peak}) = \frac{2}{D_{off}} \times I_s(\text{peak}) = \frac{2}{D_{off}} \times \frac{2 \times P_{out}}{(V_{out} + V_F)} [\text{A}] = \frac{2}{0.55} \times \frac{2 \times 18}{(55 + 1)} = 2.34[\text{A}]$$

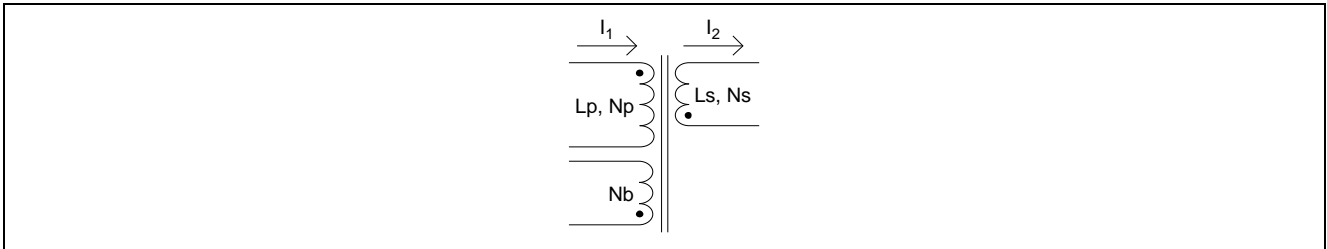


Figure 8.2 Transformer Circuit

- The inductance of the primary-side transformer, L_p , is calculated. The calculation formula is as follows in current critical mode:

$$L_p = \frac{\sqrt{2} V_{in}(\text{min}) D_{on}}{I_1(\text{peak}) f_{out}} [\text{H}] = \frac{\sqrt{2} \times 80 \times 0.45}{1.66 \times 50 \times 10^3} [\text{H}] = 613[\text{nH}]$$

A value of 600 nH is selected for inductance in accordance with the result of the calculation.

- After selected the transformer core, the number of turns in the winding of the primary-side transformer, N_p , is calculated.

$$N_p = \frac{\sqrt{2} V_{in}(\text{min}) D_{on}}{f_{sw} DB A_e} \times 10^8 [\text{T}] = \frac{\sqrt{2} \times 80 \times 0.45}{50 \times 10^3 \times 2400 \times 0.55} \times 10^8 = 77.1[\text{T}]$$

A value of 80 turns is selected for N_p in accordance with the result of the calculation.

- The inductance of the secondary-side transformer, L_s , is calculated.

$$L_s = \frac{(V_{out} + V_F)}{I_2(\text{peak})} \times \frac{D_{off}}{f_{out}} [\text{H}] = \frac{55 + 1}{2.34} \times \frac{0.55}{50 \times 10^3} [\text{H}] = 263.2[\text{nH}]$$

An value of 220 nH is selected for inductance in accordance with the result of the calculation.

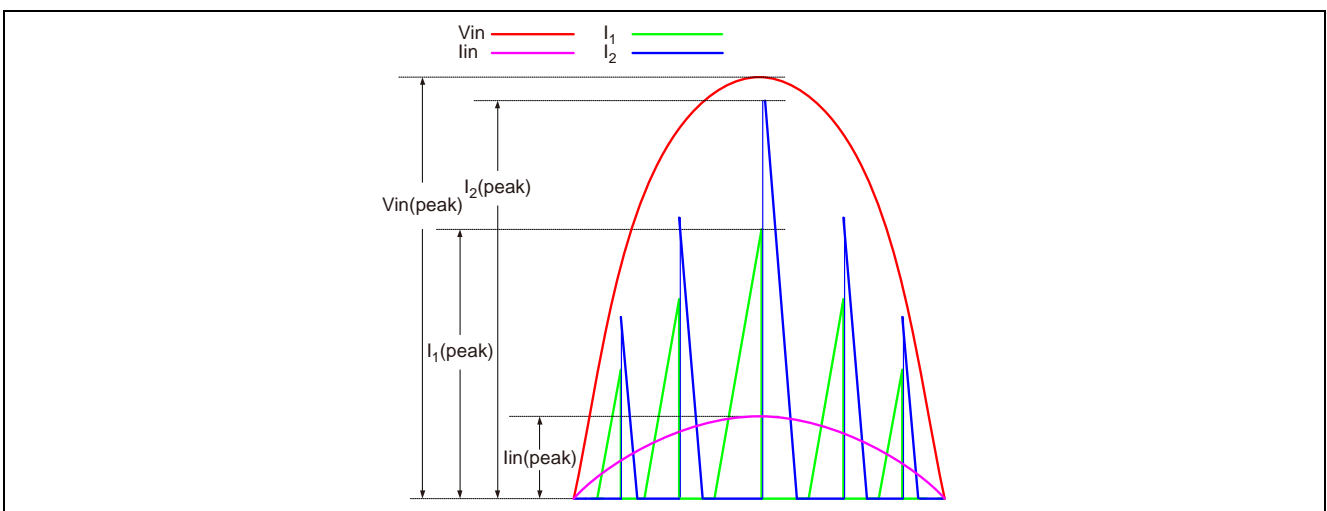


Figure 8.3 Relationship between Transformer Current, Input Current, and Input Voltage

5. The number of turns in the winding of the secondary-side transformer, N_s , is calculated.

$$N_s = \sqrt{\frac{L_s}{L_p}} N_p[T] = \sqrt{\frac{220\text{m}}{600\text{m}}} \times 80[T] = 48.4[T]$$

A value of 48 turns is selected for N_s in accordance with the result of the calculation.

6. The number of turns in the winding of the auxiliary transformer, N_b , is calculated.

$$N_b = \frac{V_b}{V_{out} + V_F} N_s[T] = \frac{20}{55 + 1} \times 48[T] = 17.1[T]$$

A value of 17 turns is selected for N_b in accordance with the result of the calculation.

$V_{in}(\text{min})$:	Minimum input voltage (actual value)	$I_{in}(\text{peak})$:	Peak value of input current	D_{on} :	On-time duty
$V_{in}(\text{peak})$:	Peak value of input voltage	A_e :	Effective cross-sectional area of the core [cm^2]	D_{off} :	Off-time duty
V_{out} :	Output voltage	DB :	Core magnetic flux density variation [G]	P_{out} :	Output power
V_F :	Diode forward voltage	f_{out} :	Switching frequency		
V_b :	Voltage across auxiliary winding	h :	Efficiency of conversion		

8.4 Selection of MOSFET (Q1)

Firstly, Drain-Source voltage of MOSFET, V_{ds} , should be calculated. At the moment of MOSFET turning off, that is V_{ds} reaching to maximum voltage, surge voltage V_k derived from transformer leakage inductance arises in addition to V_{in} and fly-back voltage V_f . When V_k is 200 V, $V_{ds}(\text{max.})$ when the MOSFET is turned off is calculated as follows:

$$V_{ds}(\text{max}) = \sqrt{2} V_{in}(\text{max}) + V_f + V_k = \sqrt{2} \times 264 + \frac{80}{48} \times (55 + 1.5) + 200 = 667.5[V]$$

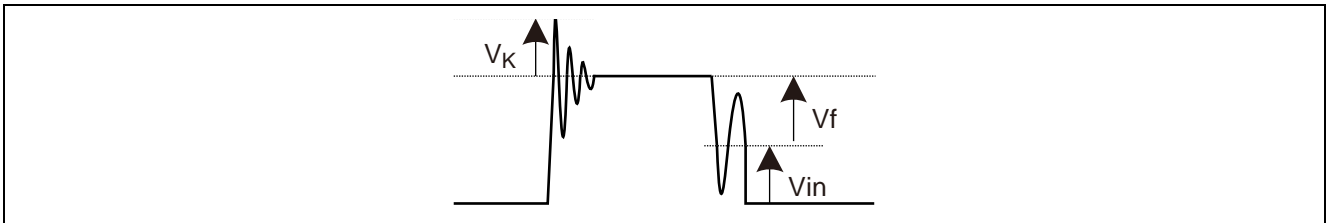


Figure 8.4 Vds Waveform of MOSFET

The peak drain current, $I_1(\text{peak})$, at minimum input voltage is calculated as follows:

$$I_1(\text{peak}) = \frac{\sqrt{2} V_{in}(\text{min}) D_{on}}{L_p f_{out}} = \frac{\sqrt{2} \times 80 \times 0.45}{600 \times 10^{-6} \times 50 \times 10^3} = 1.7[A]$$

Based on the result of the calculation, the MOSFET with voltage rating of 900 V and a rated current of 18.5 A is selected so that it operates within a range of safe operation.

Note: Please confirm if selected components' rating meet to actual operation.

8.5 Selection of Current Detection Resistor (Rcs1)

The overcurrent detection resistor Rcs1 for the primary-side overcurrent protection (OCP) is calculated as follows: Considering that the OCP threshold of IC1, V_{ocp}, is 0.6 V (typ.) and I_{1(peak)} is calculated as above, the OCP threshold is set to 3.0 A.

$$R_{cs1}[W] = \frac{V_{OCP}}{I_1(\text{peak})} = \frac{0.6}{3.0} = 0.2[W]$$

A value of 0.2 W (rated power of 2W) is selected for current detection resistor RCS in accordance with the result of the calculation.

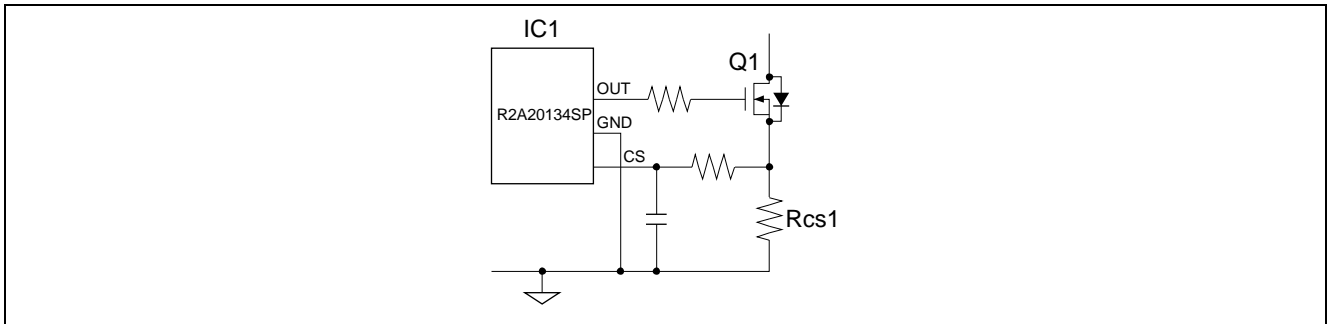


Figure 8.5 Current Detection Resistor

8.6 Selection of Output Current Setting Resistor

The resistor used to set the output current I_{out}, Rcs2, is calculated. Rcc1 and Rcc2 are determined so that the formula is satisfied.

$$R_{cs2}[W] = \frac{R_{cc2}}{R_{cc1} + R_{cc2}} \times \frac{V_{ref}}{I_{out}}$$

The charge control IC2 allows the use of a reference voltage V_{ref} (A) for the error amplifier of 1.25 V or less through the addition of an external resistor. Because the reference voltage of the IC2, V_{ref}, is 1.25 V, V_{ref} (A) is 0.33 A when R_{cc1} is 56 kW and R_{cc2} is 20 kW. Because the target for the output current I_{out} is 0.33 A, a value of 1 W is selected for current detection resistor Rcs2.

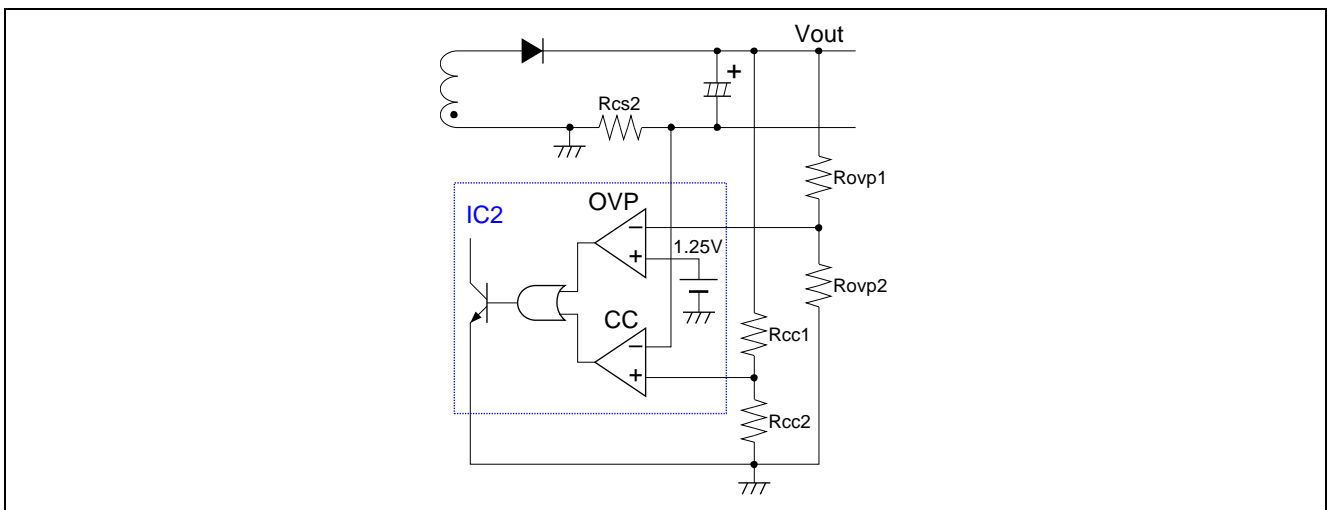


Figure 8.6 IC2 and Peripheral Circuit

8.7 Selection of Secondary-side Rectifying Diode (D1)

The maximum reverse voltage which is applied when the secondary-side rectifying diode is turn off, $V_{AK(max)}$, is calculated.

$$V_{AK(max)} = V_s + V_{out} = \frac{N_s}{N_p} \times \sqrt{2} V_{in(max)} + V_{out} = \frac{48}{80} \times \sqrt{2} \times 264 + 80 = 304[V]$$

The maximum value of the forward current, I_F , is calculated.

$$I_F(max) = \frac{2}{D_{off}} \times I_{out} = \frac{2}{0.55} \times 0.33 = 1.2[A]$$

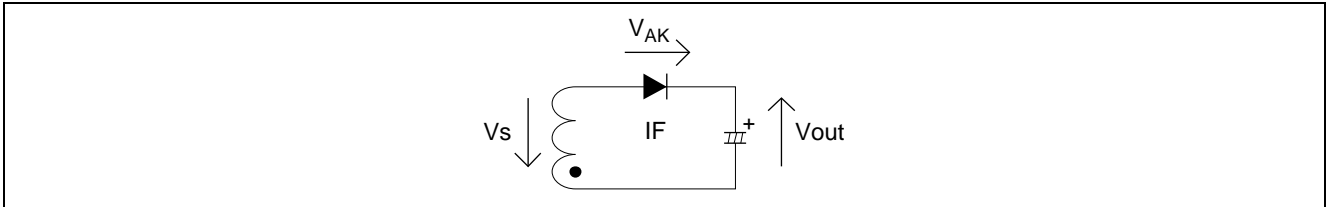


Figure 8.7 Secondary-side Rectifying Diode

Based on the above, a fast recovery diode (FRD) with rated reverse voltage of 600 V and a rated current of 2 A is selected.

Note: Please confirm if selected component's rating meet to actual operation.

8.8 Setting of Overvoltage Protection (OVP) Circuit

The constants for the overvoltage protection (OVP) circuit of the output are selected. The following is the relationship between V_{ovp} , the voltage when the output is open circuit, and R_{ovp1} and R_{ovp2} .

$$V_{ovp} = \frac{R_{ovp1} + R_{ovp2}}{R_{ovp2}} \times V_{ref}$$

V_{ovp} is set to 60 V. Then, a value of 100 kW is selected for R_{ovp1} and a value of 2.2 kW is selected for R_{ovp2} so that the above formula is satisfied.

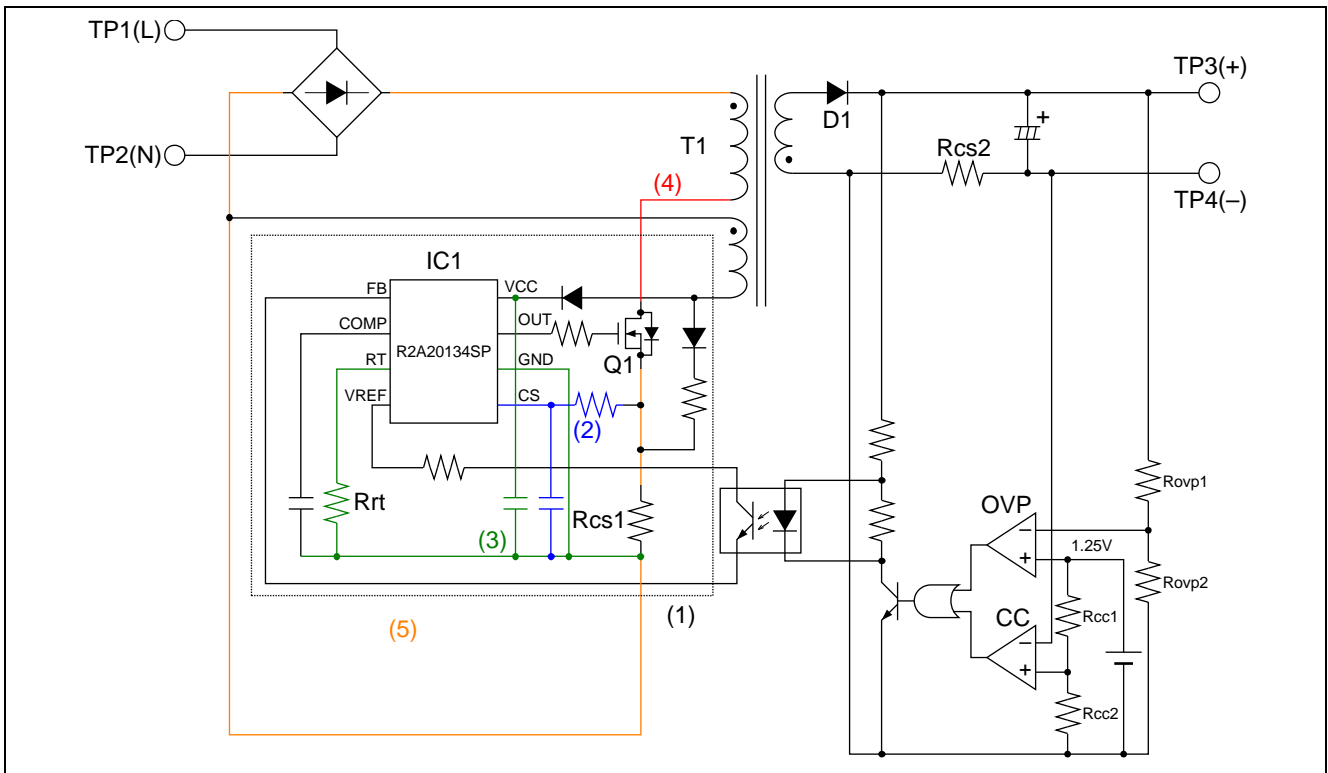
8.9 Setting of ZCD

The ZCD detection signal level is set. The voltage at the CS pin, V_{cs} , must be greater than or equal to V_{zcd} (19 mV (max.)) of IC1. In addition, current I_{cs} (–85 mA) flowing from the CS pin into R_{zcd1} and R_{cs} applies an offset to the voltage on the CS pin. Accordingly, for correct ZCD detection, the value of R_{zcd1} must satisfy the following relationship: $I_{cs} \cdot R_{zcd1} < V_{zcd}$

$$V_{cs} = \frac{R_{ZCD1} + R_{ZCD2}}{R_{ZCD2}} \times (V_b - V_F)$$

When V_{cs} is set to 0.2 V, 20 V is substituted for V_b , 0.5 V is substituted for V_F , and R_{zcd1} is set to 56 W, R_{zcd2} is 5.6 kW in accordance with the above formula.

9. PCB Layout Guidelines



- (1) Make the wiring around the IC as short as possible in order to reduce the switching noise influence.
- (2) Connect the CS line as close as possible to Rcs to shorten the wiring. Also, please place a noise suppression filter as close as possible to IC.
- (3) Wire the independent thick GND pattern of the IC as close to the Rcs1 resistor (on the output side) as possible. Also, place the VCC bypass capacitor and the RT resistor as close to the IC as possible.
- (4) To decrease the parasite inductance, connect T1 and the drain of Q1 by using independent thick and short pattern.
- (5) Make this track as thick and short as possible because the switching current flows into the wire.

Website and Support

Renesas Electronics Website

<http://www.renesas.com/>

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<http://www.renesas.com/contact/>

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Revision Record

Rev.	Date	Description	
		Page	Summary
Rev.1.00	Sep 27, 2013	—	First edition issued

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